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PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE: NEW ASSIGNMENT NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HSUAN-CHUN TSENG	01/19/2018
HSUEH-CHUN HSIAO	01/19/2018
TZU-YUN CHANG	01/19/2018
CHI-CHENG HUANG	01/19/2018
PING-CHIA SHIH	01/19/2018

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	NO. 3, LI-HSIN RD. II, SCIENCE-BASED INDUSTRIAL PARK
City:	HSINCHU
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15878278

CORRESPONDENCE DATA

Fax Number: (949)660-0809

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Correspondent Name: J.C. PATENTS

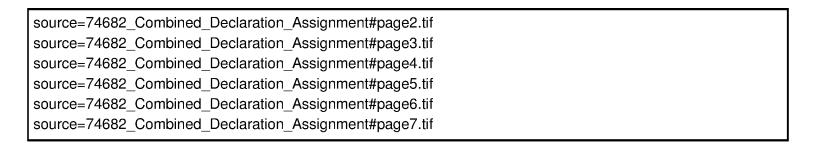
4 VENTURE, SUITE 250 Address Line 1: Address Line 4: **IRVINE, CALIFORNIA 92618**

ATTORNEY DOCKET NUMBER:	JCLA74682
NAME OF SUBMITTER:	JIAWEI HUANG
SIGNATURE:	/JIAWEI HUANG/
DATE SIGNED:	01/23/2018
	This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 7

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PATENT REEL: 044706 FRAME: 0261 504743213



PATENT REEL: 044706 FRAME: 0262

☑ Declaration Submitted With Initial Filing
OR
☐ Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)
(Title of the Invention) SEMICONDUCTOR DEVICE AND MANUFACTURING MEHOD THEREOF
As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:
This declaration is directed to:
∑ The attached application,
OR
United States Application Number or PCT International application numberFiled on
The above-identified application was made or authorized to be made by me.
I believe I am the original inventor or an original joint inventor of a claimed invention in the application.
The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

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WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS 1. United Microelectronics Corp.

of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Tseng Hsuan - Chun

Hsuan - CHun Tseng Date: <u>JAN 1 9 2018</u> Signature:

Legal Name of Sole or First Inventor: Hsuan-Chun Tseng

Residence: Taipei City, Taiwan

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	He we of the	Hundh	Chun	Herao					
Signature:	348101	1 700			Date:	JAN	19	2018	

Legal Name of Additional Joint Inventor, if any: Hsueh-Chun Hsiao

Residence: Hsinchu County, Taiwan

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Signature:	Zi	<u>U</u>	un	Cha	~ {	Date:	JAN	1	9	2018	
					-0						

Legal Name of Additional Joint Inventor, if any: Tzu-Yun Chang

Residence: Hsinchu County, Taiwan

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(R.O.C.)

Signature:	Chr Cheng	Huang	Date:	JAN 1	9 2018	
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UMCD-2017-0661 74682-US-PA

DECLARATION AND ASSIGNMENT FOR UTILITY OR DESIGN PATENT APPLICATION

Signature:	they	Chia	Shih	Date:	JAN 1 9 2018	
Legal Name of	f Additional Join	t Inventor, it	any: Ping-Chia	Shih		

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